

Specifications

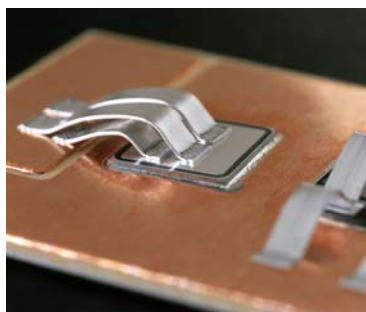
Mechanics

<i>X, Y table</i>	Working area 100 x 100 mm Resolution 0,25 µm, repeatability < 2 µm
<i>Z-axis</i>	60 mm
<i>Speed</i>	All axes programmable from 0, 2...16 mm/s ≤ 30 wires / min.
<i>Bond head</i>	Wedge-Wedge Alu- Heavy Ribbon and Alu-wire Axis of rotation ± 360° 90° quick-change wire guide and cutter Bondforce programmable up to 3500cN
<i>Ultrasonic system</i>	60 KHz
<i>Ribbonsize</i>	from 500µm X 75µm up to 2000µm X 300µm
<i>Wire size</i>	100µm to 500 µm
<i>Loop Forms</i>	Triangular, rectangular, reverse, stitch bond programmable

Controls

<i>Computer</i>	Single-Board PC, 600 MHz Pentium processor, 256 MB RAM, Ethernet, USB 4x, CD-ROM
<i>Monitor</i>	17" TFT flat screen
<i>Operation system</i>	Windows 2000
<i>Printer</i>	All Windows-compatible printers can be installed All bonding parameters can be printed
<i>Work holder</i>	2"x2" standard with mechanical clamping 4"x4" optional, as well with vacuum

Rev. 07
04_2007



5650 HR

Semi-automatic Heavy Ribbon-Wedge-Bonder

The semi-automatic Wedge-Wedge Bonder 5650HR fills the gap between the manual Wedge-Bonders series 54xx from F&K Delvotec Semiconductor to the automatic bonder from F&K Delvotec.

On basis of the 5600-series the bonder is fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various samples in order to perform a single bond.(manual-automatic) Multi wire for teaching and bonding of single chips or various samples (semi and fully automatic).

The 5650 can also be used as a Au Wire or AL Thin Wire Bonder as well as pull/shear tester by simply replacing the bond head and loading the appropriate software.

change over time: approx. 3 minutes. Ask us for information !

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Other features

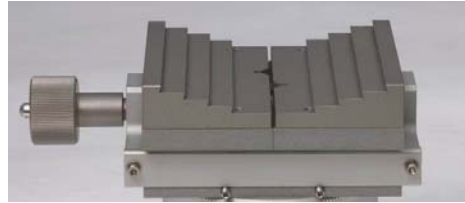
Programming:

Automatic bonding of hybrids, power modules or others with programmable X/Y table

Work holders



for components 2" x 2"
mechanical clamping



for components 4" x 4"
mechanical clamping



for components 4" x 4"
mechanical clamping and vacuum

Customised work holders are available on request.

Head Parking System

For storing of temporary not required bondheads or pull- and shear-heads.
Can be mounted on the left or right side of the machine

General

Camera

With cross hair targeting for positioning of bonds

Microscope

Stereoscope Motic, other microscopes e.g. Leica optional

Lighting

20 W halogen spot light, optional LED direct light
Incident light optional

Dimensions

Height 70 cm, width 70 cm, depth 65 cm; approx. 70 kg

Supplies

100...240 VAC, single-phase, 50/60 Hz, max. 500 VA

Connections

Air 6 bar, vacuum - 0,7 bar \varnothing 6 mm

Optional

DLC DeformationLimitControl

PRU Structur and Greelevel

Retrofit-head 56xx

Bondhead 5650

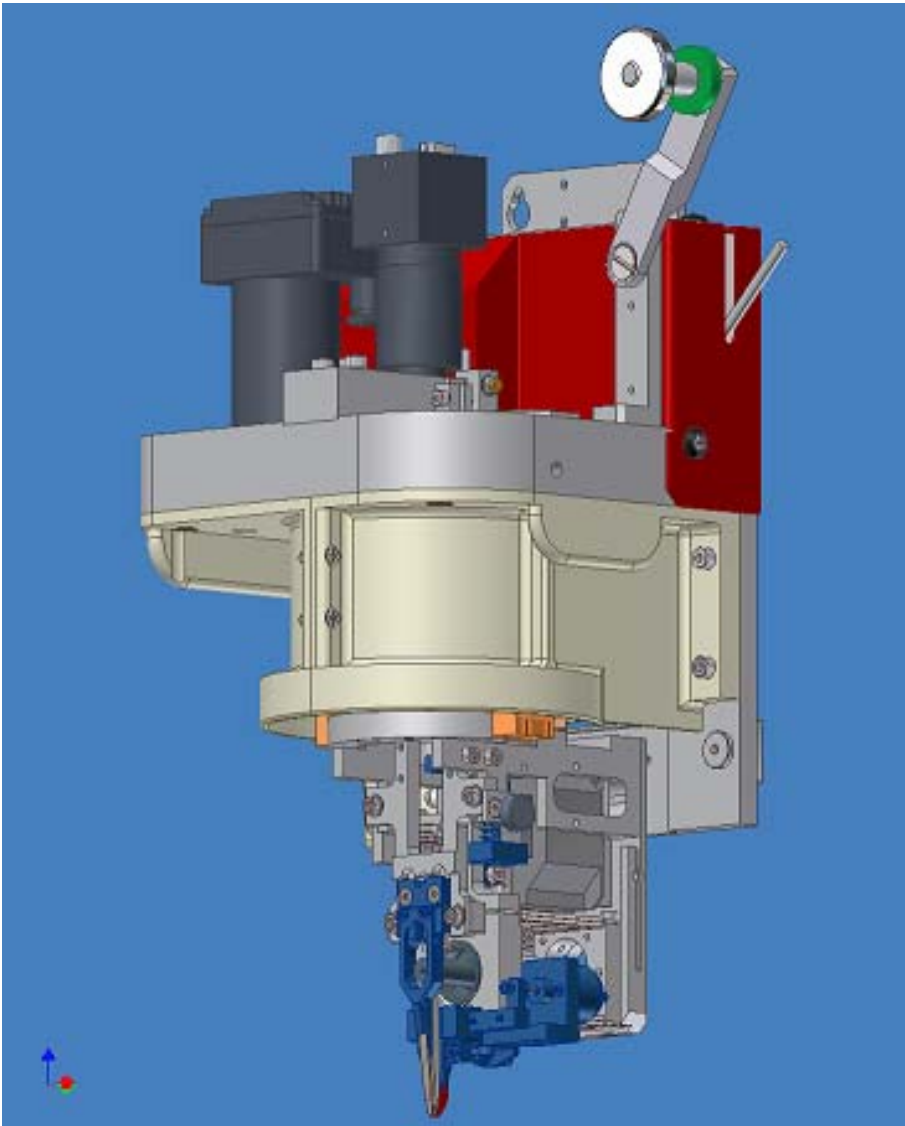
Ribbon tools 2"

Cutter system Front-cut

Ribbon size up to 2000µm X 300µm

Wire size (Al/CU) 100 µm – 500 µm

Wedge/Wedge Axis of rotation ± 360°



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